



Product Change Notification

Change Notification #: 118084 - 00
Change Title: Select Intel® Optane™ Memory H10 with Solid State Storage, PCN 118084-00, Label, Label Update
Date of Publication: March 2, 2021

Key Characteristics of the Change:

Label

Forecasted Key Milestones:

Date Customer Must be Ready to Receive Post-Conversion Material:	April 1, 2021
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Description of Change to the Customer:

Intel® Optane™ Memory H10 with Solid State Storage series SKUs listed in the Products Affected Table below will have the following changes.

- Change 1 – Generic Pizzabox label (MOQ1)
- Change 2 - Generic Disitbox label (MOQ1)

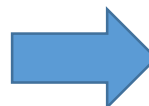
Change1 : Generic Pizzabox label (MOQ1)

Current Label



 QTY: 1 
MM #: XXXXXX **SN: VSPPYWWDXXXXNNNFGN**
Pb-free 2LI MADE IN CHINA WITH PARTIAL FOREIGN CONTENT PACKED BY:XXXXXX


SSDXXXXXXXXXX 
CARTON #: XXXXXXXXX 8 89296 11254 9
BATCH #: XXXXXXXXX
VERSION #: XXXXX-XXX
PACK DATE: XX XXX XX **Model: XXXXXXXXXXXXX**






New Label




 QTY: 1 
MM #: XXXXXX **SN: VSPPYWWDXXXXNNNFGN**
Pb-free 2LI MADE IN XXXXX WITH PARTIAL FOREIGN CONTENT PACKED BY:XXXXXX

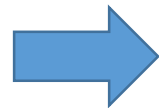
SSDXXXXXXXXXX 
CARTON #: XXXXXXXXX 8 89296 11254 9
BATCH #: XXXXXXXXX
VERSION #: XXXXX-XXX
PACK DATE: XX XXX XX **Model: XXXXXXXXXXXXX**


UK Intel Corporation (UK) Ltd,
CP Attn: Corp Quality, Pipers Way,
PA Swindon, Wiltshire SN3 1RJ, UK



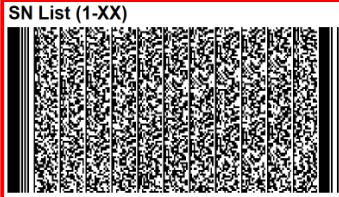
Change2 : Generic Disitbox label (MOQ1)

Current Label

SSDXXXXXXXXXX **Carton # List (1-XX)** 
MM #:XXXXXX  QTY:XX
BOX #:XXXXXXXXXX
BATCH #:XXXXXXXXXX
VERSION #:XXXXXX-XXX
PACK DATE :DD MMM YY
MADE IN CHINA WITH PARTIAL FOREIGN CONTENT **Model: XXXXXXXXXXXXX**
PACKED BY:XXXXXX Pb-free 2LI 



New Label

MODEL: XXXXXXXXXXXXX **Carton # List (1-XX)** 
MM #: XXXXXX  QTY: XX
BOX #: XXXXXXXXX
BATCH #: XXXXXXXXX
FW: XXXXXXXX **SN List (1-XX)** 
PACKED BY: XXXXXXXX PACK DATE: DD MMM YY
MADE IN XXXXX WITH PARTIAL FOREIGN CONTENT

Customer Impact of Change and Recommended Action:

There is no change to the form, fit, or function of the product. The change is only to the labels used in packaging.

Customers should be aware of the changes to the label and take appropriate actions to accommodate the changes and avoid impact to their process.

Milestone dates are estimates and subject to change based on business and operational conditions.

Products Affected / Intel Ordering Codes:

Marketing Name	Product Code	MM#
Intel® Optane™ Memory H10 with Solid State Storage (32GB + 1TB, M.2 80mm PCIe 3.0, 3D XPoint™, QLC) Generic Single Pack	HBRPEKNX0203A01	984684
Intel® Optane™ Memory H10 with Solid State Storage (16GB + 256GB, M.2 80mm PCIe 3.0, 3D XPoint™, QLC) Generic Single Pack	HBRPEKNX0101A08	999MJ9
Intel® Optane™ Memory H10 with Solid State Storage (32GB + 512GB, M.2 80mm PCIe 3.0, 3D XPoint™, QLC) Generic Single Pack	HBRPEKNX0202A08	999MJF
Intel® Optane™ Memory H10 with Solid State Storage (32GB + 1TB, M.2 80mm PCIe 3.0, 3D XPoint™, QLC) Generic Single Pack	HBRPEKNX0203A08	999MJG

PCN Revision History:

Date of Revision:

March 2, 2021

Revision Number:

00

Reason:

Originally Published PCN



Product Change Notification

118084 - 00

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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

Americas Contact: asmo.pcn@intel.com

Asia Pacific/PRC Contact: apacgccb@intel.com

Europe Email: eccb@intel.com

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